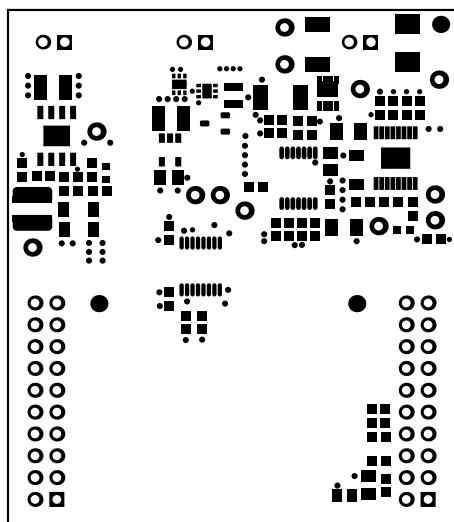
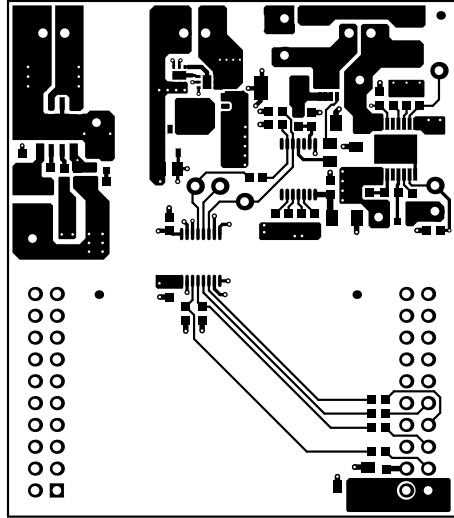


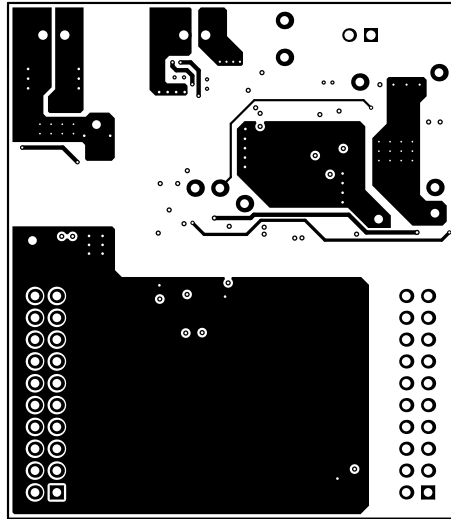
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01621		
PLOT NAME = Top Overlay	GENERATED : 5/8/2018	4:22:21 PM	TEXAS INSTRUMENTS



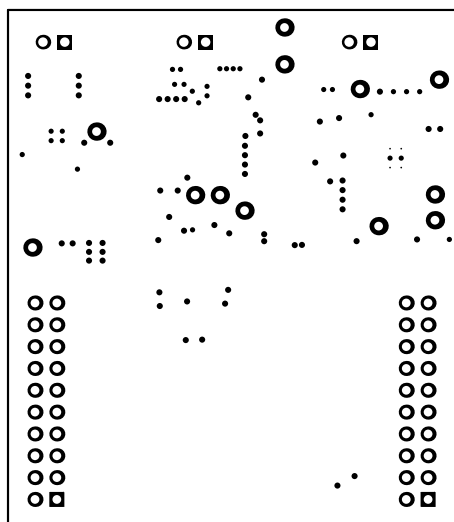
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01621		
PLOT NAME = Top Solder Mask	GENERATED : 5/8/2018 4:22:23 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01621		
PLOT NAME = Top Layer	GENERATED : 5/8/2018	4:22:24 PM	TEXAS INSTRUMENTS



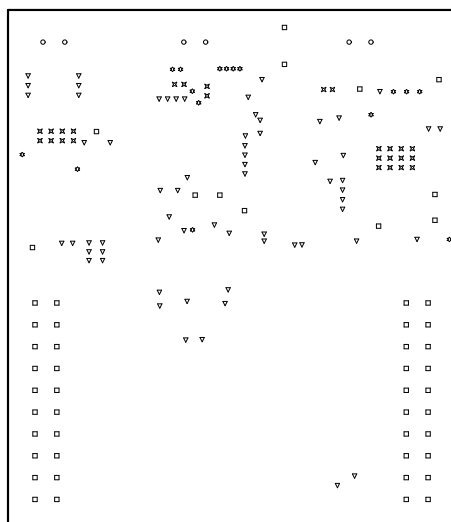
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01621		
PLOT NAME = Bottom Layer	GENERATED : 5/8/2018	4:22:25 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01621		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/8/2018	4:22:26 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01621		
PLOT NAME = Bottom Overlay	GENERATED : 5/8/2018	4:22:27 PM	TEXAS INSTRUMENTS

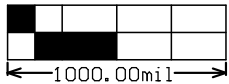
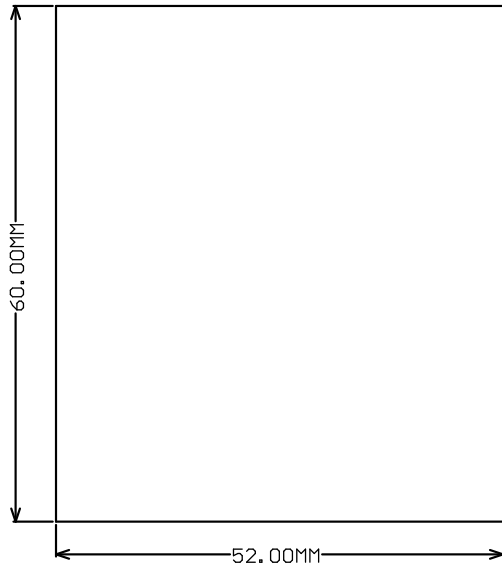


Drill Table:

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Via/Pad
☆	26	7.87mil (0.200mm)	PTH	Round	Via
⬠	16	10.00mil (0.254mm)	PTH	Round	Via
▽	65	12.00mil (0.305mm)	PTH	Round	Via
□	52	40.00mil (1.016mm)	PTH	Round	Pad
○	6	43.31mil (1.100mm)	PTH	Round	Pad
	165 Total				

Tolerance:
 For 7.87mil via +0/-7.87mil
 For 10mil via +0/-10mil
 For 12mil via +0/-12mil
 For PTH Drill +/-3mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01621		
PLOT NAME = Drill Drawing	GENERATED : 5/8/2018	4:22:28 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01621	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01621		
PLOT NAME = Board Dimensions	GENERATED : 5/8/2018	4:22:30 PM	TEXAS INSTRUMENTS

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